

Trina Solar Signs Equipment Supply Contract With Meyer Burger AG

Press Release October 4, 2007 Greentech Media

Trina Solar Limited ([NYSE:TSL](#)) ("Trina Solar" or the "Company"), a leading integrated manufacturer of solar photovoltaic products from the production of ingots, wafers and cells to the assembly of PV modules, announced today that it has signed an agreement with Meyer Burger AG for the supply of ID cropping, band and wire saws used for the production of its monocrystalline and multicrystalline wafers and cells. The contract, valued over CHF180 million (US\$154million), covers equipment and delivery schedule to meet the Company's capacity expansion goals through 2010.

"We are pleased to enter into this supply agreement with Meyer Burger and to work with one of the most successful manufacturers of high-precision machines for slicing silicon into wafers," stated Mr. Jifan Gao, Trina Solar's Chairman and Chief Executive Officer. "Both Meyer Burger and Trina Solar share a commitment to the highest level of quality for our products and we look forward to working together in the future."

"We are pleased to be able to support Trina Solar with the latest ID/OD, band and wire saw technology as it expands its wafer capacity and makes progress on its technology roadmap to reduce wafer thickness," stated Peter Pauli, Meyer Burger's CEO. "We expect our subsidiary company Meyer Burger Machinery Shanghai to provide Trina Solar with the necessary level of customer support and quality assurance and we look forward to continue our successful cooperation in the future."

www.trinasolar.com